## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: Todd O. Bolken

Serial No.: 09/516,080

Filed: March 1, 2000

Assistant Commissioner

Washington, D.C. 20231

for Patents

For: EXPOSED DIE MOLDING

**APPARATUS** 

Group Art Unit: 2814

Examiner:

Louie, W.

Atty Docket: MICS:0043 FLE/MAN

99-0634

CERTIFICATE OF MAILING 37 C.F.R. 1.8

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on the date below:

March 1, 2002

Date

Sir:

## RESPONSE AND AMENDMENT

In response to the Official Action mailed on December 5, 2001, Applicants respectfully request reconsideration of the above-identified application in view of the remarks and amendments set forth below.

## IN THE DRAWINGS

In Figs. 6A and 6B, replace reference numeral 90 with reference numeral 95.

## IN THE CLAIMS

Please amend claims 1, 5, 9, 10 and 11 as set forth below:

1. (once amended) A system for molding a circuit package comprising: